

ABSTRACT

A recessed-bond semiconductor package substrate including a plurality of dielectric layers and a plurality of metal layers, wherein the metal layers further include a first metal layer and at least one underlying metal layer, and wherein the underlying metal layer is configured for a direct interconnection with a semiconductor die. Preferably, the top metal layer includes a ground plane. An underlying metal layer comprises the signal layer, which is preferably bonded to the die by a plurality of bond wires.